

## **Quarterly Reliability Monitoring Results**

## Quarters: Q1/2022 to Q4/2023

Based on structural similarity

Supplier		User Part Number					
Nexperia B.V.  Name of Laboratory  Assembly reliability labs  Based on AEC-Q101 Test		BZB84-B3V9-Q Part Description					
		SMD package					
		Test Conditions	Duration	# Lots	# Quantity	# Rejects	
			TEST				
	Pre- and Post-Stress						
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below	
		JESD22-A113					
		Bake Tamb = 125 °C	24 hours				
	PC	Soak Tamb = 85 °C, RH = 85%	168 hours				
# A1	Preconditioning	Reflow soldering	3 cycles	1514	64430	0	
		MIL-STD-750-1					
	HTRB	M1038 Method A					
	High Temperature Reverse	Tj = Tjmax, VR = 80 % of rated reverse					
# B1	Bias	voltage	1000 hours	250	11400	0	
		MIL-STD-750-1					
		M1038 Method B					
	SSOP	Tj = Tjmax, Iz = 100% of max. datasheet					
# B1b	Steady State Operational	reverse current	1000 hours	44	1920	0	
	TC	JESD22-A104					
# A4	Temperature Cycling	-65 °C to Tjmax, not to exceed 150°C	1000 cycles	311	14080	0	
	UHAST	JESD22-A118					
# A3 <b>or</b>	Unbiased HAST	Tamb = 130 °C, RH = 85 %	- 96 hours	311	14080	0	
		JESD22-A102					
	AC	Tamb = 121 °C, RH = 100 %					
# A3 alt	Autoclave	Pressure = 205 kPa (29.7 psia)					
	H3TRB	JESD22-A101					
	High Humidity High	Tamb = 85 °C, RH = 85%, VR = 80 % of				_	
# A2 alt	Temperature Reverse Bias	rated reverse voltage <sup>[1]</sup>	1000 hours	311	14080	0	
		MIL-STD-750 Method 1037					
	IOL	ton = toff, devices powered to insure $\Delta Tj$ =					
# A5	Intermittent Operating Life	100 °C for 15000 cycles	1000 hours	312	14120	0	
	RSH	JESD22-A111					
# C8	Resistance to Solder Heat		10 s	269	8070	0	
# 6	SD	200 0 = 3 0	10.5	209	0070	U	
# C10	Solderability	J-STD-002		19	6660	0	
# C10	Solderability	J J1D 002		19	0000	U	

<sup>[1]</sup> The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

## **Calculation of FIT and MTTF**

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Zener	11400	0	0,37	2,68E+09

<sup>© 2024</sup> Nexperia B.V.

All information hereunder is per Nexperia's best knowledge. This document does not provide for any representation or warranty express or implied by Nexperia. In case Nexperia has tested the product, this documentation reflects the outcome of the analysis of the actually tested parts only.

nexperia.com